

Title of Change:	SOIC8 Assembly Transfe Semiconductor	SOIC8 Assembly Transfer of the NB3U1548CDG and NB3U1548CDR2G from SPEL to ON Semiconductor		
Proposed First Ship date:	14 Jul 2021 or earlier if approved by customer			
Contact Information:	Contact your local ON Semiconductor Sales Office			
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or < <u>PCN.samples@onsemi.com</u> >. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.			
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Nhel.Malonzo@onsemi.com			
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <u>PCN.Support@onsemi.com</u>			
Marking of Parts/ Traceability of Change:	Affected products will be identified with date code from new assembly site.			
Change Category:	Assembly Change			
Change Sub-Category(s):	Manufacturing Site Transfer			
Sites Affected:				
ON Semiconductor Sites		External Foundry/Subcon Sites		
ON Semiconductor Carmona, Philippines		SPEL Semiconductor Limited		
Description and Dumpson				

Description and Purpose:

Transfer assembly from SPEL to ON Semiconductor which includes change in Leadframe design, die attach material, mold material and bond wire diameter.

	Before Change Description	After Change Description	
Lead Frame	SOIC8 95X130 Cu	SOIC8 256 U/S LEADFRAME	
Die Attach	CRM1076NS Ablestik ABP 8062T		
Bond Wire	0.8 mil Au 1.0 mil Au		
Mold Compound	G633 G700LS		
Assembly Site	SPEL Semiconductor Limited	ON Semiconductor Carmona, Philippines	

No package dimension change and no product performance change.



Reliability Data Summary:

QV DEVICE NAME: <u>NB3U1548CDG</u> RMS: <u>60762</u>, 72534 and 74640 PACKAGE: SOIC8

PACKAGE: SU	168			
Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta= 125°C, 120% nominal Vcc	1008 hrs	0/240
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/239
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc	0/264
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/240
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/238
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C		0/747
PD	JESD22-B100 and B108			0/30
SD	JSTD002	Ta = 245C, 5 sec		0/45

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle	
NB3U1548CDR2G	NB3U1548CDG	
NB3U1548CDG	NB3U1548CDG	